

LOGIC SYNTHESIS OF VLSI CIRCUITS

© *Giovanni De Micheli*

Stanford University

Microelectronics

© GDM

- Enabling and strategic *technology*.
- Primary markets:
 - Information systems.
 - Telecommunications.
 - Consumer.
- Secondary markets:
 - Systems (e.g., transportation).
 - Manufacturing (e.g., robots).
- Application of VSLI circuit technology.

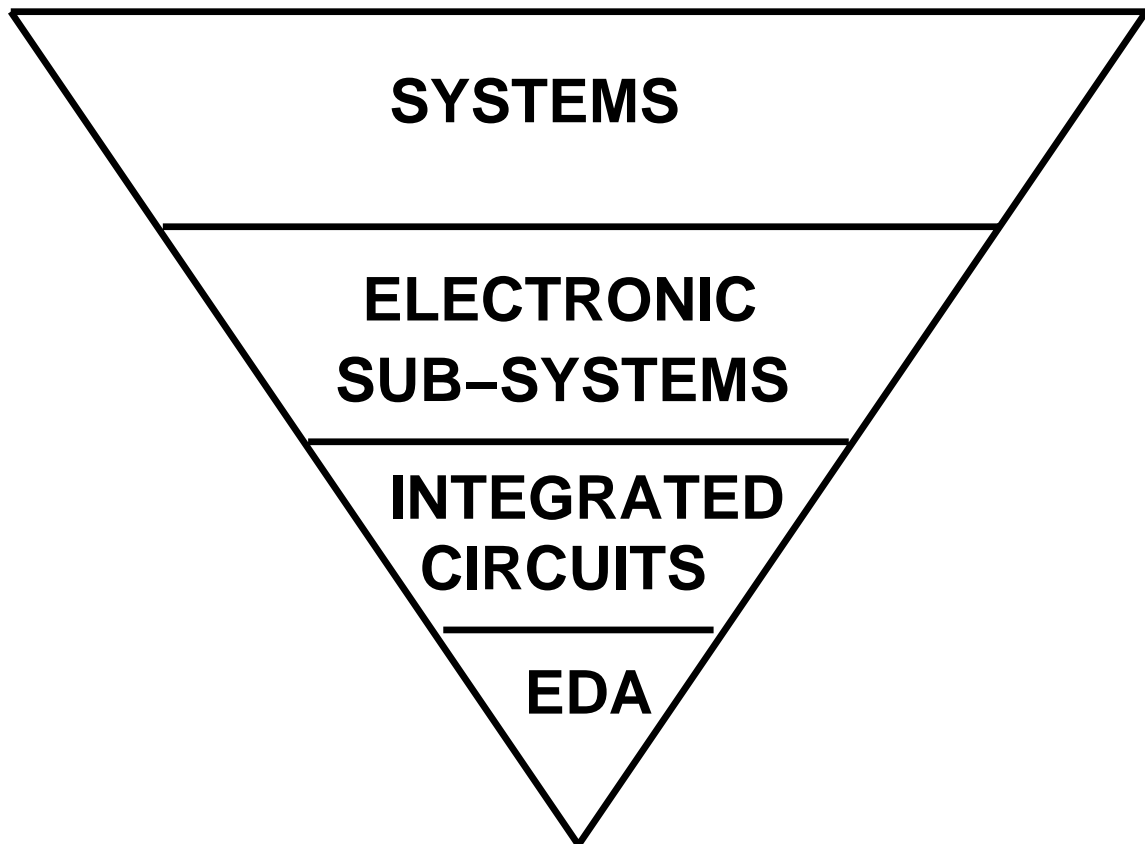
Computer-Aided Design

© GDM

- Enabling design *methodology*.
- Makes electronic design possible:
 - Large scale design management.
 - Design optimization.
 - Reduced design time.
- Key strategic importance.

Electronic market

© GDM



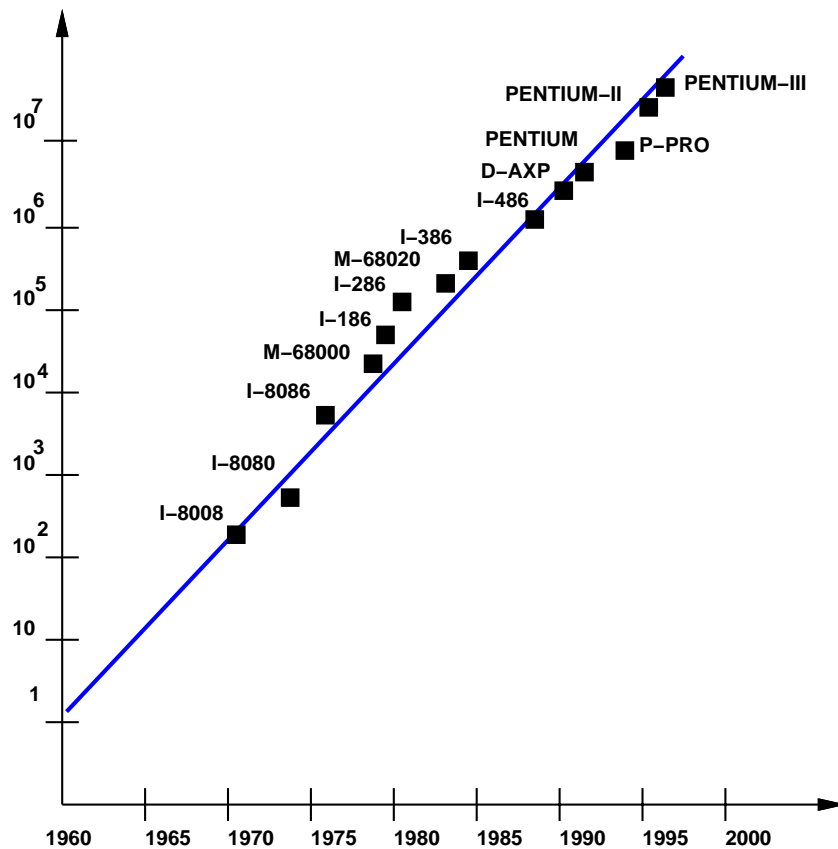
Trends in microelectronics

© GDM

- Improvements in device technology:
 - Smaller circuits.
 - Higher performance.
 - More devices on a chip.
- Higher degree of integration.
 - More complex systems.
 - Lower cost of computation.
 - Higher reliability.

Moore's law

© GDM



Integration-scale limitations

© GDM

- Intrinsic physical scaling limits.
- Capital investment for fabrication.
 - Use of appropriate design styles.
- Large-scale design management.
 - Use of CAD design tools.

Microelectronic design problems

© GDM

- Use most recent technologies.
 - To be competitive in performance.
- Reduce design cost.
 - To be competitive in price.
- Speed-up design time.
 - Time-to-market is critical.

Microelectronic economics

© GDM

- Design cost:
 - *Design time and fabrication cost.*
 - *Large capital investment.*
 - *Near impossibility to repair.*
- Recapture costs:
 - *Large volume production is beneficial.*
 - *Zero-defect designs are essential.*
 - *Follow market evolution.*

Microelectronic circuits

© GDM

- General-purpose processors:
 - High-volume sales.
 - High performance.
- Application-Specific Integrated Circuits (ASICs):
 - Varying volumes and performances.
- Prototypes.
- Special applications (e.g. space).

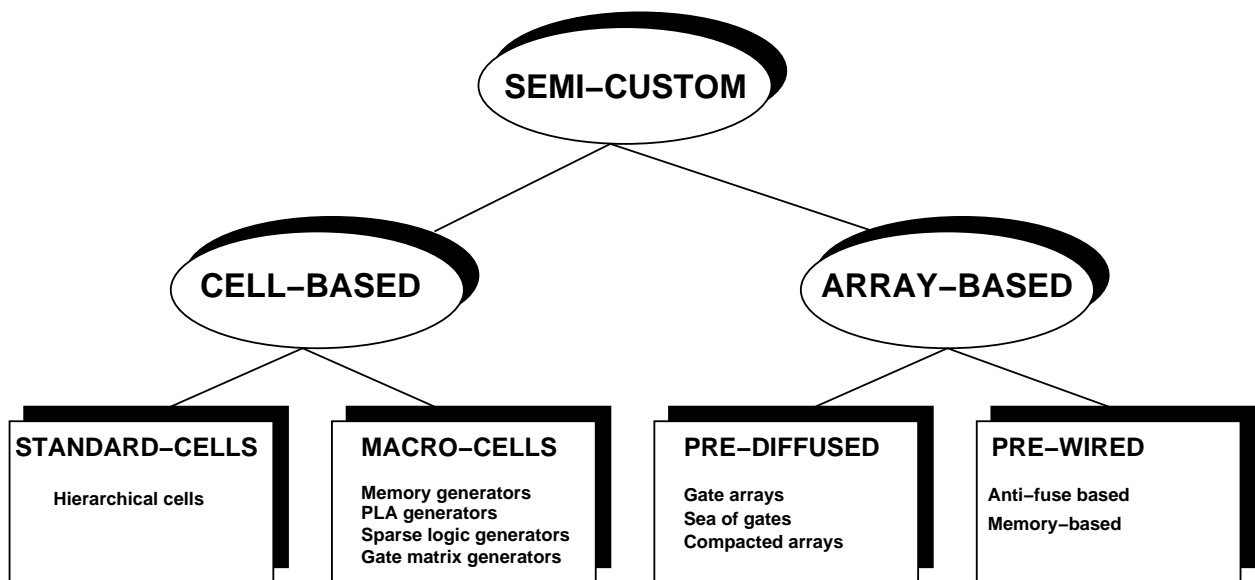
Microelectronic design styles

© GDM

- Adapt circuit design style to market requirements:
- Parameters:
 - Cost.
 - Performance.
 - Volume.
- Custom and semi-custom design.

Semicustom design

© GDM



Standard cells

© GDM

- Cell library:
 - Cells are designed once.
 - Cells are highly optimized.
- Layout style:
 - Cells are placed in rows.
 - Channels are used for wiring.
- Compatible with macro-cells (e.g. RAMs).

Macro-cells

© GDM

- Module generators:
 - Synthesized layout.
 - Variable area and aspect-ratio.
- Examples:
 - RAMs, ROMs, PLAs, general logic blocks.
- Features:
 - Layout can be highly optimized.
 - Structured-custom design.

Array-based design

© GDM

- *Pre-diffused* arrays:
 - Personalization by metalization/contacts.
 - Mask-Programmable Gate-Arrays.
- *Pre-wired* arrays:
 - Personalization on the field.
 - Field-Programmable Gate-Arrays.

MPGAs

© GDM

- Array of *sites*:
 - Each site is a set of transistors.
- Batches of wafers can be pre-fabricated.
- Few masks to personalize chip.
- Lower cost than cell-based design.

FPGAs

© GDM

- Array of cells:
 - Each cell performs a logic function.
- Personalization:
 - Soft: memory cell (e.g. Xilinx).
 - Hard: Anti-fuse (e.g. Actel).
- Immediate turn-around (for low volumes).
- Inferior performances and density.
- Good for prototyping.

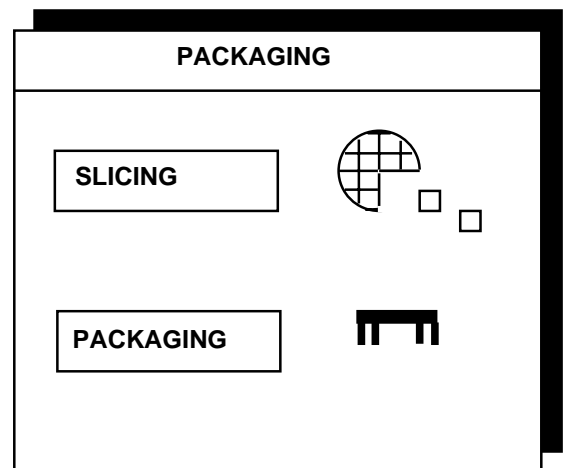
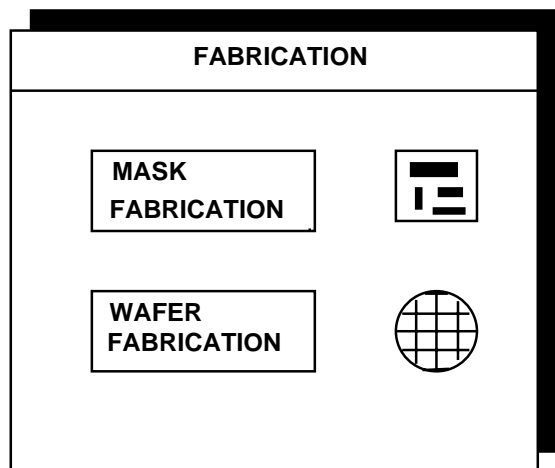
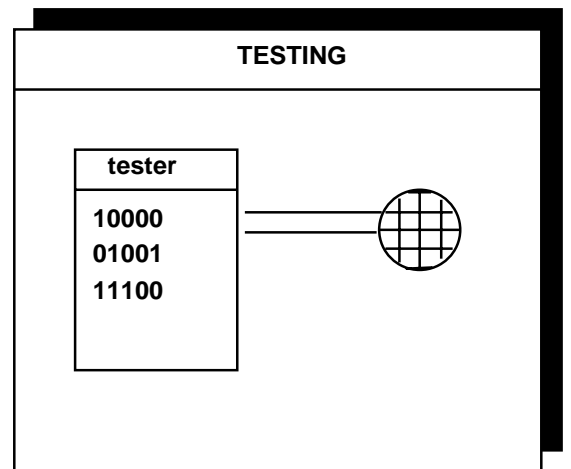
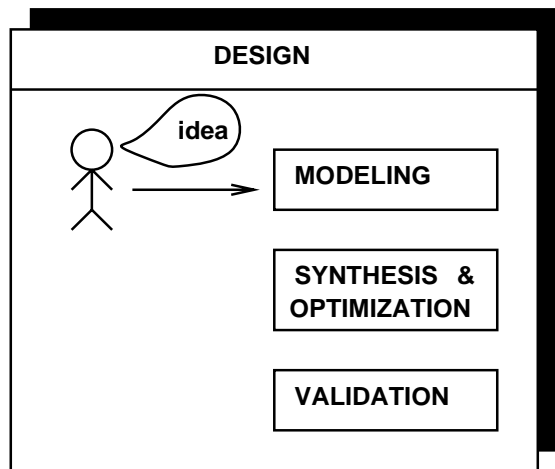
Semi-custom style trade-off

© GDM

	<i>Custom</i>	<i>Cell-based</i>	<i>Pre-diff.</i>	<i>Pre-wired</i>
Density	Very High	High	High	Medium-Low
Performance	Very High	High	High	Medium-Low
Flexibility	Very High	High	Medium	Low
Design time	Very Long	Short	Short	Very Short
Man. time	Medium	Medium	Short	Very Short
Cost - lv	Very High	High	High	Low
Cost - hv	Low	Low	Low	Medium-High

Microelectronic circuit design and production

© GDM



Microelectronic circuit design

© GDM

- Conceptualization and modeling:
 - Hardware Description Languages (HDLs).
- Synthesis and optimization:
 - Model refinement.
- Validation:
 - Check for correctness.

© GDM

© GDM

ARCHITECTURAL LEVEL

...

PC = PC + 1;

FETCH (PC);

DECODE (INST);

...

ARCHITECTURAL LEVEL

...

PC = PC + 1;

FETCH (PC);

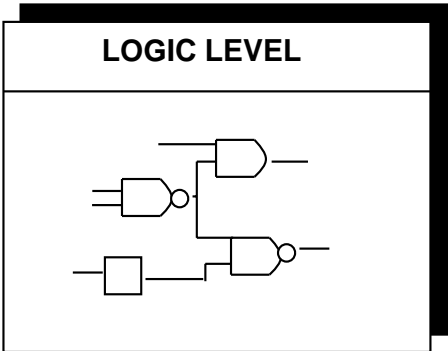
DECODE (INST);

...

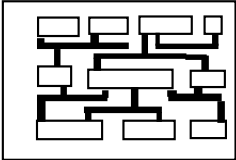
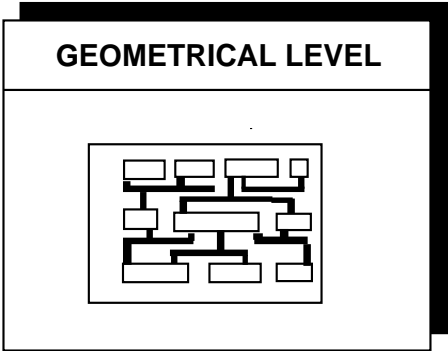
LOGIC LEVEL

The diagram illustrates a logic circuit with the following components and connections:

- An input line splits into two paths.
- The top path goes through an AND gate (represented by a D-shaped symbol).
- The bottom path goes through an OR gate (represented by a symbol with a curved input side and a pointed output side).
- The output of the OR gate is connected to the input of a NOT gate (represented by a triangle with a small circle at its tip).
- The output of the NOT gate is connected to the input of the AND gate.
- The output of the AND gate is the final output of the circuit.



GEOMETRICAL LEVEL

A complex geometric diagram consisting of a grid of rectangles connected by thick black lines, forming a network-like structure. The diagram is enclosed in a rectangular border. It features several horizontal and vertical rectangles of varying sizes, interconnected by thick black lines that create a series of paths and junctions. The overall shape is roughly rectangular, with the internal connections forming a dense, interconnected web.

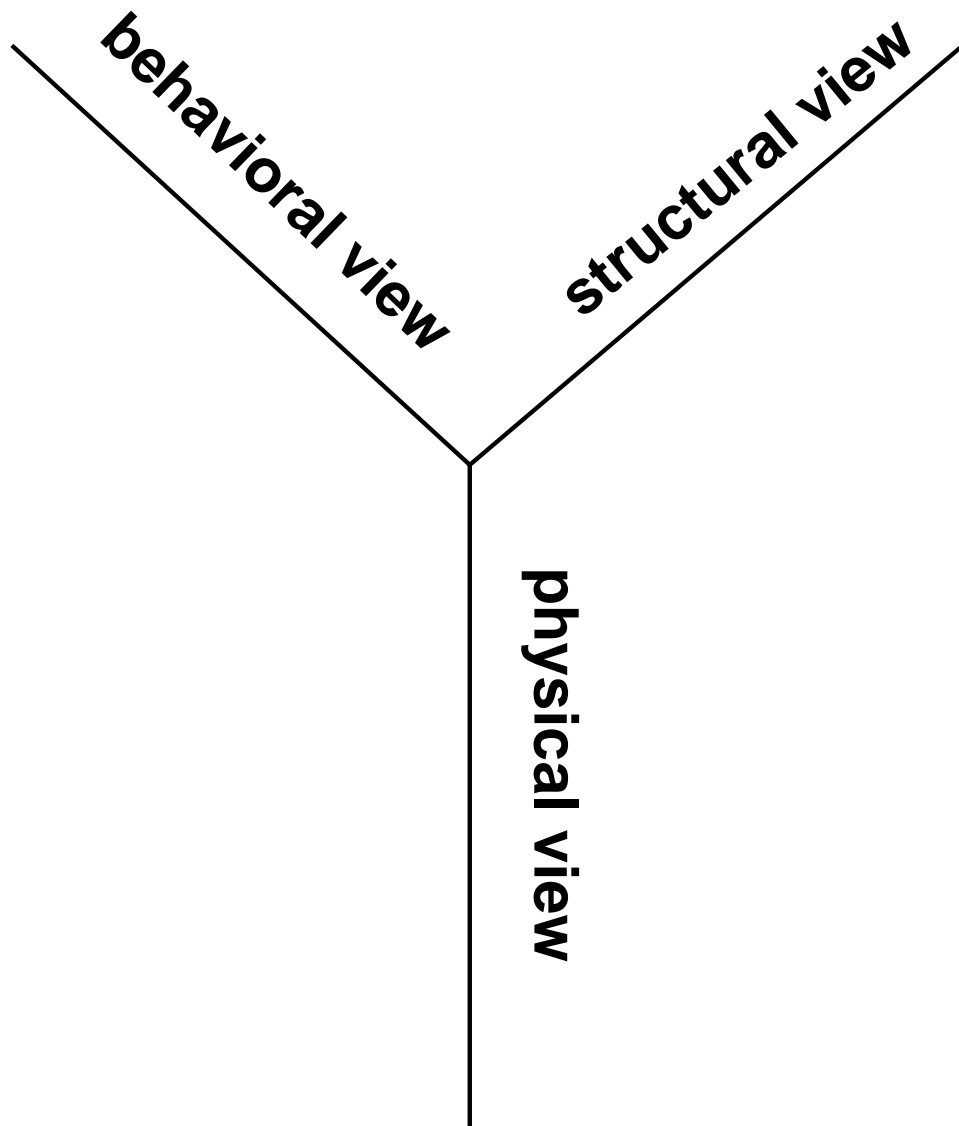
Modeling abstractions

© GDM

- *Architectural level:*
 - Operations implemented by resources.
- *Logic level:*
 - Logic functions implemented by gates.
- *Geometrical level:*
 - Devices are geometrical objects.

Modeling views

© GDM



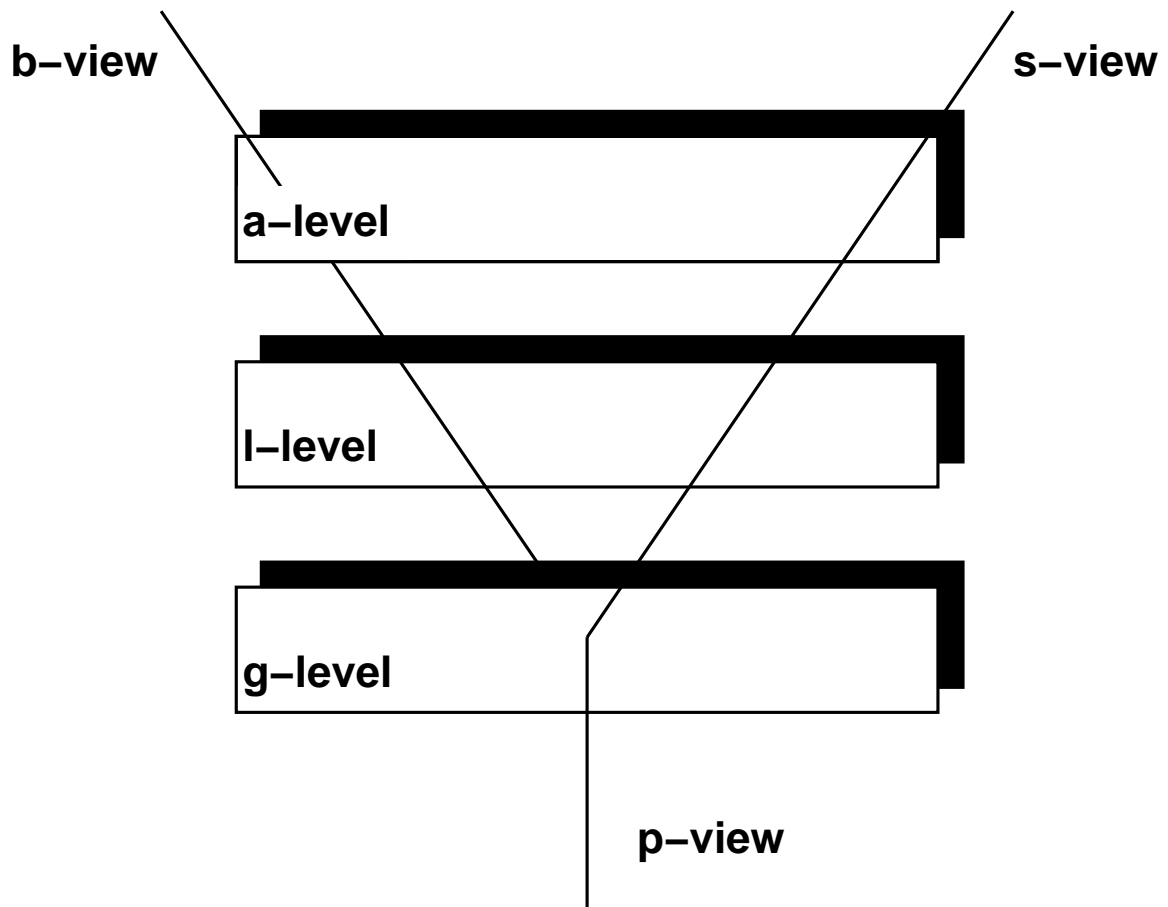
Modeling views

© GDM

- *Behavioral view:*
 - Abstract function.
- *Structural view:*
 - An interconnection of parts.
- *Physical view:*
 - Physical objects with size and positions.

Modeling views and abstractions

© GDM



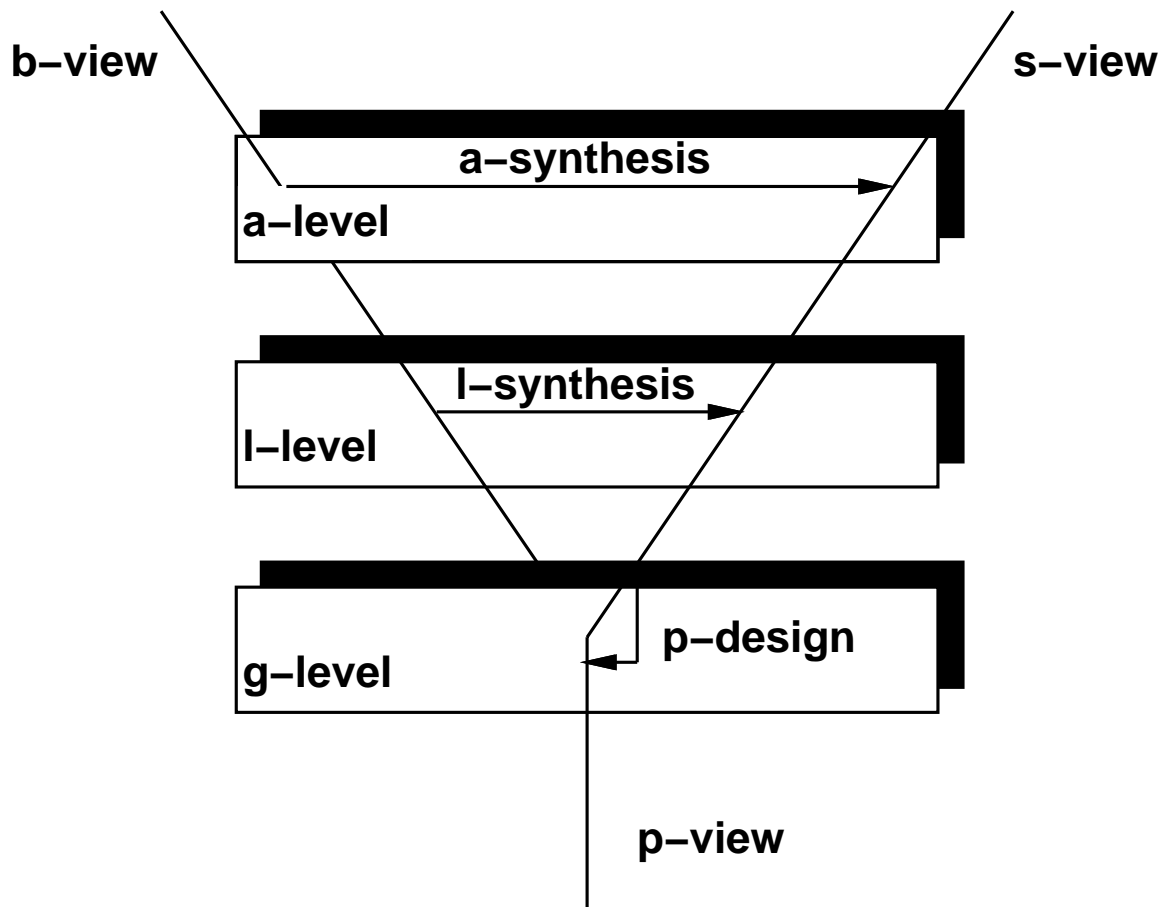
Circuit synthesis

© GDM

- *Architectural-level synthesis:*
 - Determine the macroscopic structure:
 - * Interconnection of major building blocks.
- *Logic-level synthesis:*
 - Determine the microscopic structure:
 - * Interconnection of logic gates.
- *Geometrical-level synthesis:*
(Physical design)
 - Determine positions and connections.

Modeling views

© GDM



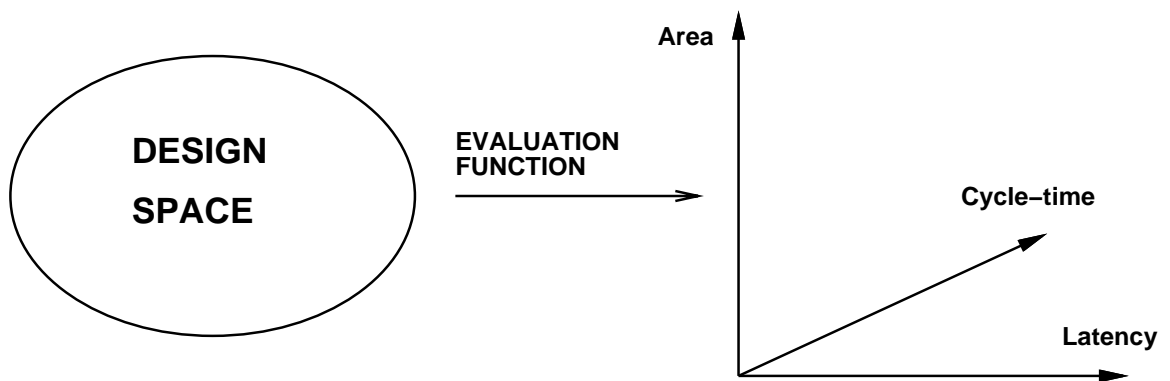
Microelectronic circuit optimization

© GDM

- *Performance:*
 - Delay and cycle-time.
 - Latency.
 - Throughput (for pipeline applications).
- *Power consumption.*
- *Area (yield and packaging cost).*
- *Testability.*

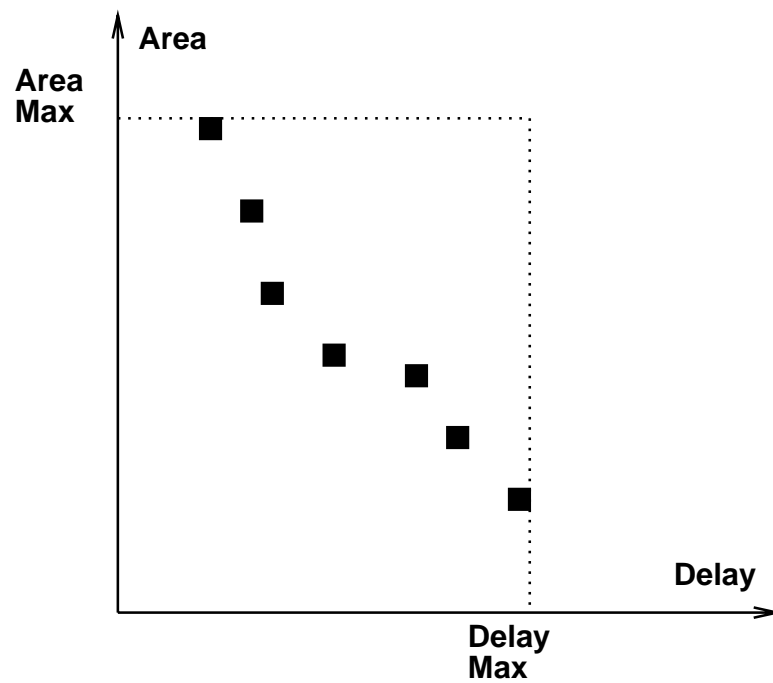
Design space and evaluation space

© GDM



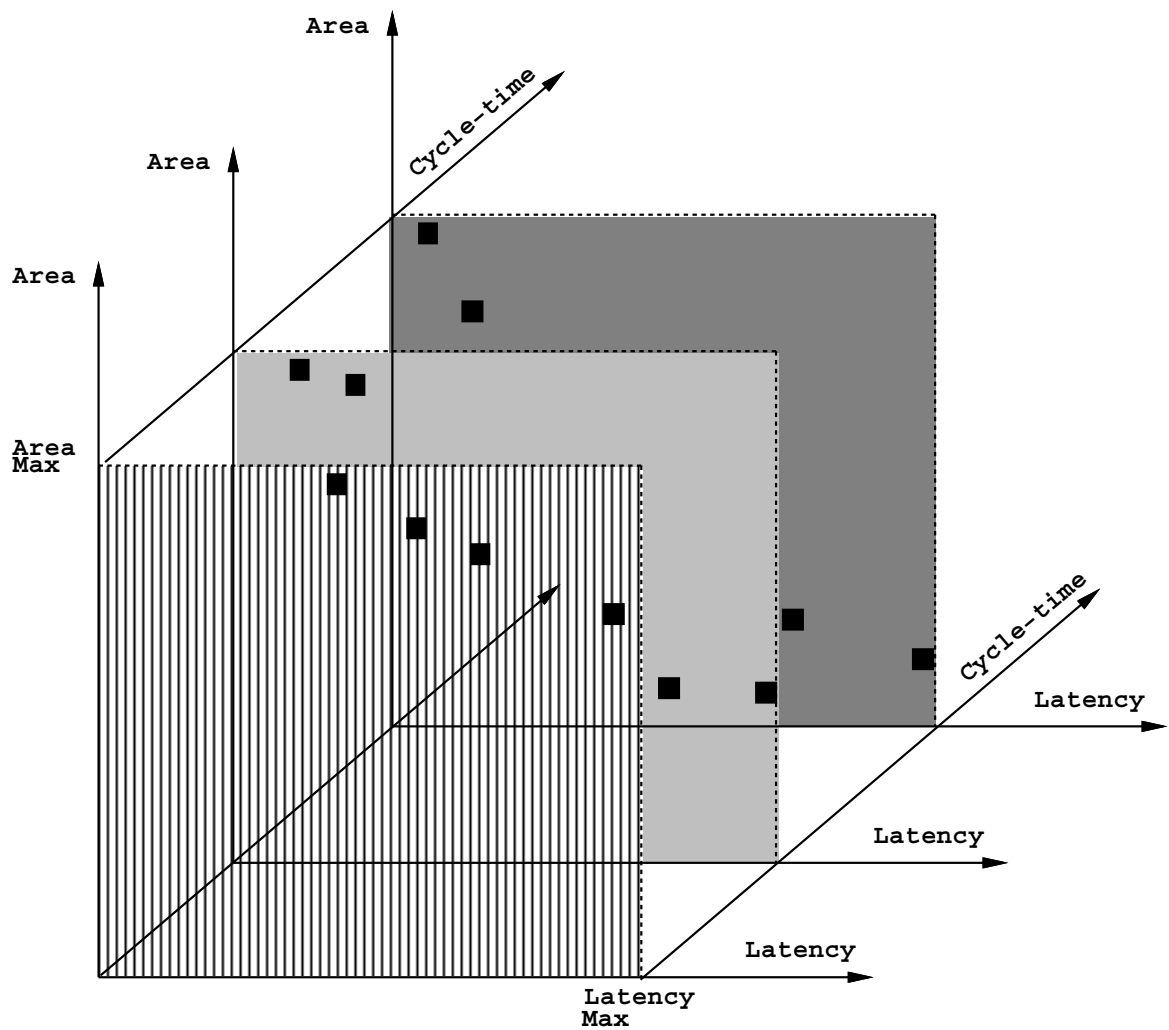
Optimization trade-off in combinational circuits

© GDM



Optimization trade-off in sequential circuits

© GDM



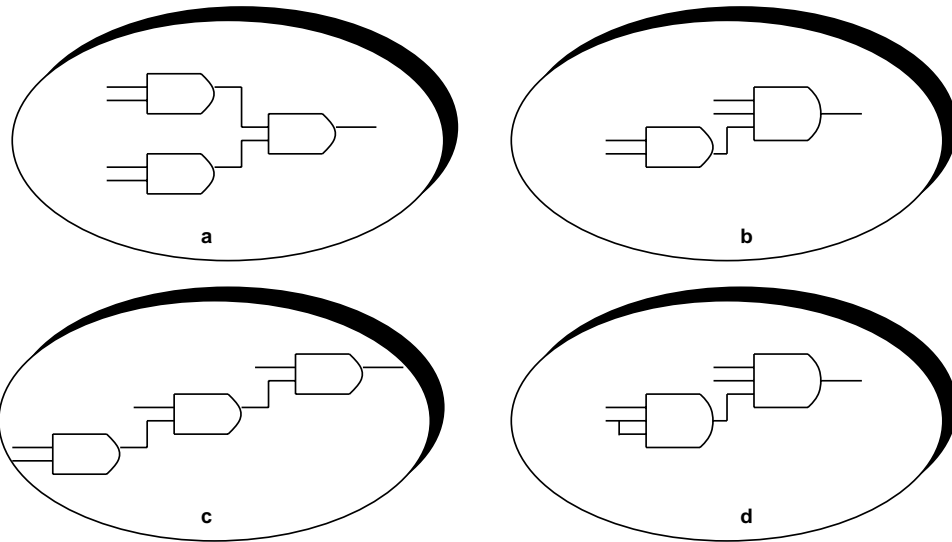
Pareto points

© GDM

- Multi-criteria optimization.
- Multiple objectives.
- *Pareto point*:
 - A point of the design space is a Pareto point if there is no other point with:
 - * at least one inferior objectives.
 - * all other objectives inferior or equal.

Example design space

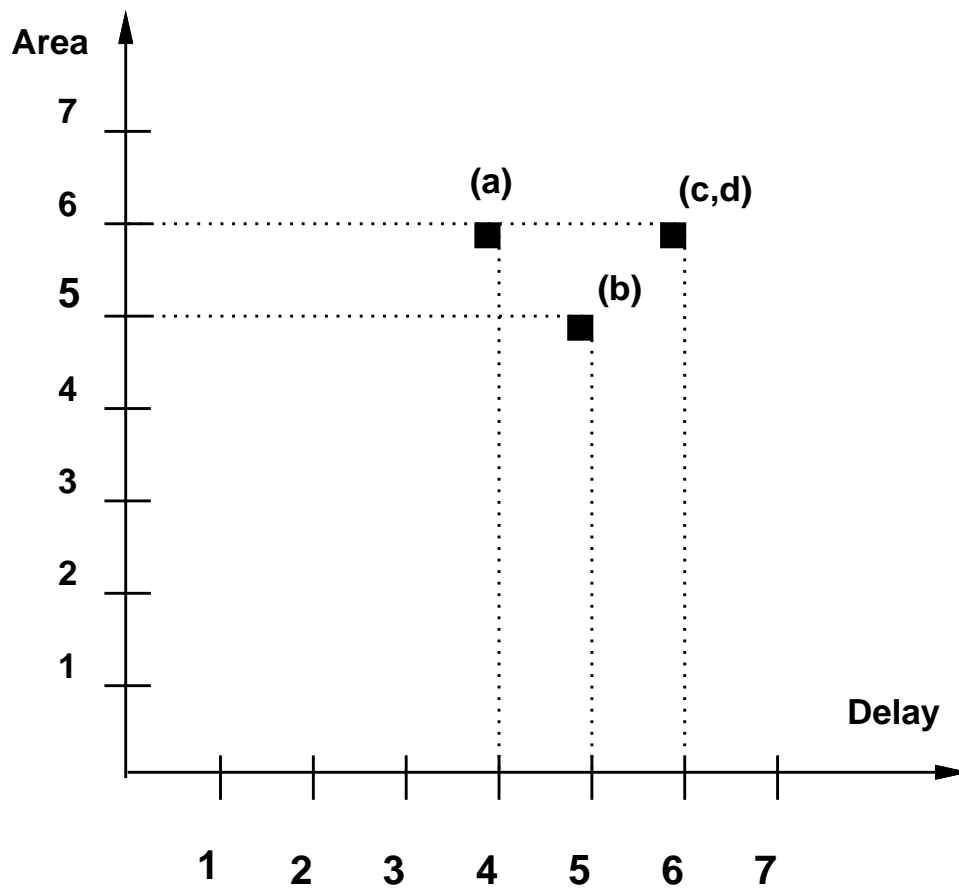
© GDM



- Implement $f = p q r s$ with:
 - 2-input or 3-input *AND* gates.
- Area and delay proportional to number of inputs.

Example design evaluation space

© GDM



Summary

© GDM

- Computer-aided design methodology:
 - Capture design by HDL models.
 - Synthesize more detailed abstractions.
 - Optimize circuit parameters.
- Logic synthesis and optimization:
 - Manipulate and optimize circuit models at the logic abstraction levels.